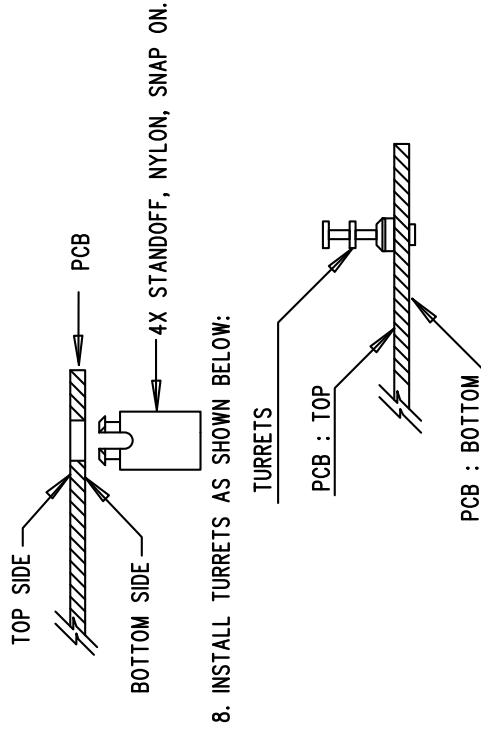
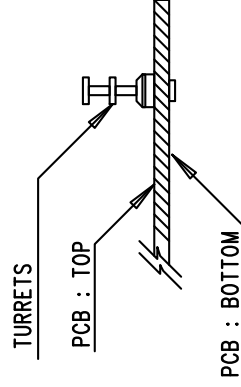



1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
3. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
5. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
6. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
7. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
8. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
9. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
10. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



**8. INSTALL TURRETS AS SHOWN BELOW:**



		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408) 432-1800 <a href="http://www.linear.com">www.linear.com</a> LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY	
TITLE: TOP ASSEMBLY DRAWING DUAL SEPIC OR INVERTING $\mu$ MODULE DC/DC CONVERTER			
SIZE N/A	IC NO. LTM8049EY	REV. 4	
FILENAME: DC2244A-4.PCB		SHT 1 OF 2	